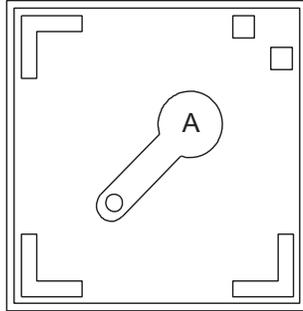


# CPD65-BAV45

## Low Leakage Diode Die

### 50mA, 35 Volt

The CPD65-BAV45 is a silicon 50mA, 35 Volt diode ideal for low leakage applications.



#### MECHANICAL SPECIFICATIONS:

Die Size	11.8 x 11.8 MILS
Die Thickness	8.0 MILS
Anode Bonding Pad Size	2.35 MILS DIAMETER
Top Side Metalization	Al – 15,000Å
Back Side Metalization	Au – 18,000Å
Scribe Alley Width	2.5 MILS
Wafer Diameter	4 INCHES
Gross Die Per Wafer	75,000

#### MAXIMUM RATINGS: (T<sub>A</sub>=25°C)

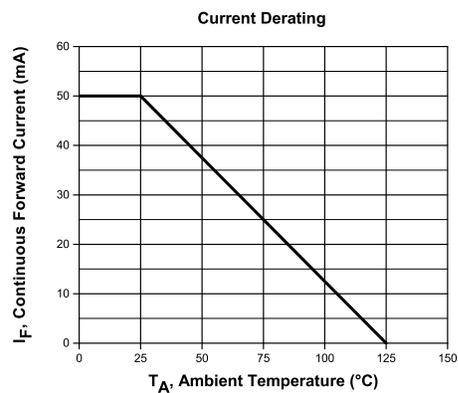
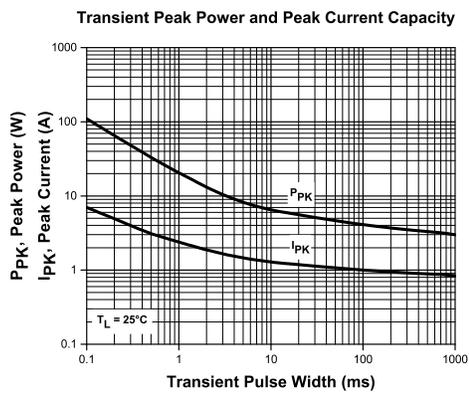
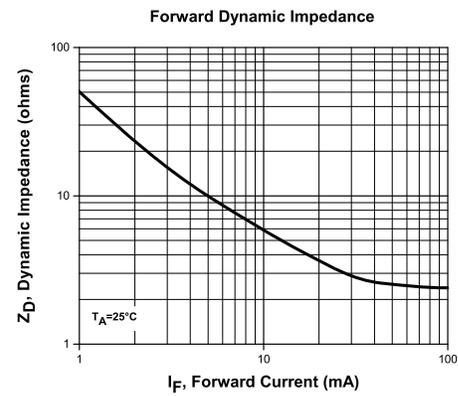
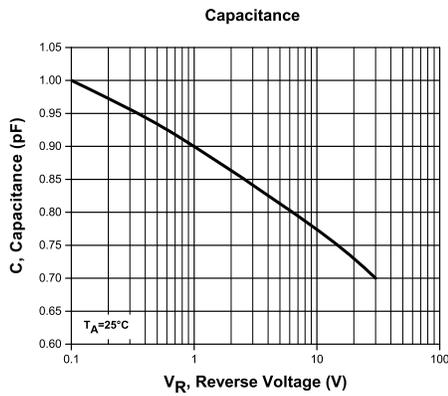
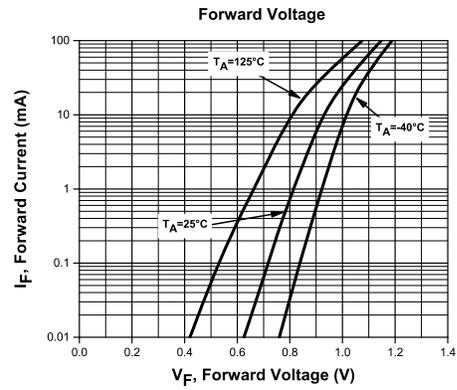
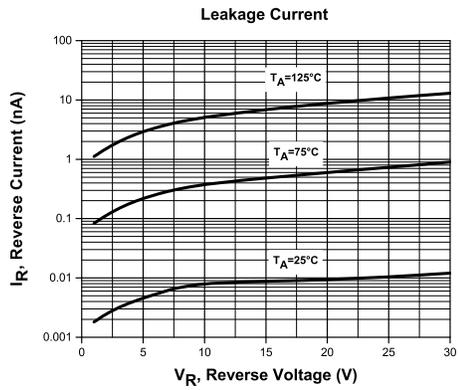
	SYMBOL		UNITS
Peak Repetitive Reverse Voltage	V <sub>RRM</sub>	35	V
Continuous Reverse Voltage	V <sub>R</sub>	20	V
Continuous Forward Current	I <sub>F</sub>	50	mA
Peak Repetitive Forward Current	I <sub>FRM</sub>	100	mA
Operating and Storage Junction Temperature	T <sub>J</sub> , T <sub>stg</sub>	-65 to +125	°C

#### ELECTRICAL CHARACTERISTICS: (T<sub>A</sub>=25°C unless otherwise noted)

SYMBOL	TEST CONDITIONS	MIN	MAX	UNITS
I <sub>R</sub>	V <sub>R</sub> =5.0V		5.0	pA
I <sub>R</sub>	V <sub>R</sub> =20V		10	pA
V <sub>F</sub>	I <sub>F</sub> =10mA		1.0	V
C <sub>J</sub>	V <sub>R</sub> =0, f=1.0MHz		1.3	pF
t <sub>rr</sub>	I <sub>F</sub> =I <sub>R</sub> =10mA, I <sub>rr</sub> =1.0mA, R <sub>L</sub> =100Ω		600	ns

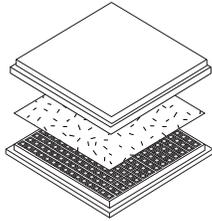
# CPD65-BAV45

## Typical Electrical Characteristics



## BARE DIE PACKING OPTIONS

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### BARE DIE IN TRAY (WAFFLE) PACK

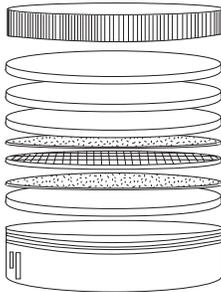
**CT:** Singulated die in tray (waffle) pack.

(example: CP211-PART NUMBER-CT)

**CM:** Singulated die in tray (waffle) pack 100% visually inspected as per MIL-STD-750, (method 2072 transistors, method 2073 diodes).

(example: CP211-PART NUMBER-CM)

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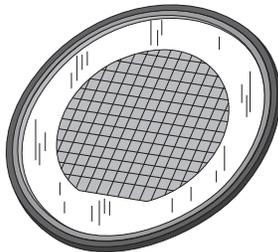


### UNSAWN WAFER

**WN:** Full wafer, unsawn, 100% tested with reject die inked.

(example: CP211-PART NUMBER-WN)

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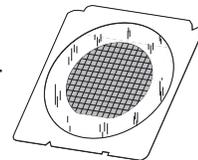


### SAWN WAFER ON PLASTIC RING

**WR:** Full wafer, sawn and mounted on plastic ring, 100% tested with reject die inked.

(example: CP211-PART NUMBER-WR)

Please note: Sawn Wafer on Metal Frame (WS) is possible as a special order. Please contact your Central Sales Representative at 631-435-1110.



R1 (10-February 2017)

## OUTSTANDING SUPPORT AND SUPERIOR SERVICES



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### PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- Inventory bonding
- Consolidated shipping options
- Custom bar coding for shipments
- Custom product packing

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### DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free quick ship samples (2<sup>nd</sup> day air)
- Online technical data and parametric search
- SPICE models
- Custom electrical curves
- Environmental regulation compliance
- Customer specific screening
- Up-screening capabilities
- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- Application and design sample kits
- Custom product and package development

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### CONTACT US

#### Corporate Headquarters & Customer Support Team

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